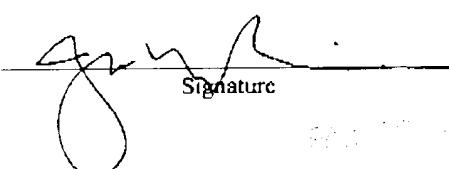


IN THE UNITED STATES PATENT AND TRADEMARK OFFICESerial No.: **09/627,979**Examiner: **DiLinh Nguyen**Inventor: **Randy H. Y. Lo, Chi-Chuan Wu and Ssu-Cheng Lai**Filed: **June 24, 2000**Art Unit: **2814**Title: **Method Of Packaging Multi Chip Module**Certificate of Transmission under 37 CFR 1.8

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SignatureFEB 28 2002
PTOCommissioner for Patents
Washington, D.C. 20231

Sir:

AMENDMENT A

In response to the Office Action mailed **12/03/2001**, please amend the above-identified application as follows:

SPECIFICATION:

Page 1, lines 4-8, amend the paragraph as:

The present invention relates to a method of packaging an integrated circuit (IC) package, and particularly, to a low cost and high reliability method of packaging a plurality of bare chips and CSP(Chip Scale Package) on a substrate for a multi chip module package (MCM package) so as to increase the package density.

Page 1, lines 11-16, amend the paragraph as: